

**IN THE CLAIMS**

1 (currently amended) A method of making a microelectronic interposer comprising the steps of:

(a) providing a body defining a first surface;

(b) providing a first sacrificial ~~temporary~~ layer over said first surface;

(c) forming apertures passing through said body and said first sacrificial ~~temporary~~ layer;

(d) depositing a layer of an electrically conductive structural material in each said aperture and over said first sacrificial ~~temporary~~ layer proximate said aperture to thereby form contacts; and

(e) removing said first sacrificial ~~temporary~~ layer, leaving said contacts with outwardly flaring peripheral portions spaced vertically above said first surface of said body.

2. (currently amended) The A-method as claimed in claim 1, further comprising ~~the~~ step of depositing a first layer of adhesive on said first surface of said body before providing said first sacrificial ~~temporary~~ layer, said sacrificial ~~temporary~~ layer being provided over said adhesive layer, whereby said adhesive layer is left exposed after said step of removing said sacrificial ~~temporary~~ layer.

3. (currently amended) The A-method as claimed in claim 2, wherein said adhesive layer is formed from an adhesive selected from the group consisting of thermoplastic adhesives and b-staged adhesives.

4. (currently amended) The A-method as claimed in claim 2, wherein said adhesive layer is formed from a thermoplastic selected from the group consisting of polyimide and polyetherimide.

5. (currently amended) The A-method as claimed in claim 1, wherein said sacrificial temporary-layer is formed from a metal selected from the group consisting of aluminum, tin, and nickel.

6. (currently amended) The A-method as claimed in claim 1, wherein said body further defines a second surface opposite said first surface; said method further comprising the step of providing a second sacrificial temporary-layer over said second surface; said apertures passing through said second sacrificial temporary-layer; and said deposited structural material extends over said second sacrificial temporary-layer proximate said apertures to thereby form second contacts.

7. (withdrawn) A method of making a microelectronic interposer comprising the steps of:

- (a) providing a body defining a first surface;
- (b) providing a first compliant layer over said first surface;
- (c) forming apertures passing through said body and said compliant layer;
- (d) depositing a layer of an electrically conductive structural material in each said aperture and over said compliant layer proximate said aperture to thereby form contacts with outwardly flaring peripheral portions on said compliant layer.

8. (withdrawn) A method as claimed in claim 7, wherein said compliant layer comprises an adhesive.

9. (withdrawn) A method as claimed in claim 7, further comprising partially etching said compliant layer whereby said compliant layer has a thickness under said contacts greater than a thickness between said contacts.